



# SOT1197-1

DFN2626-10: plastic thermal enhanced extremely thin small outline package; no leads; 10 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HXSON10
<b>Package type industry code</b>	DFN2626-10
<b>Package style descriptive code</b>	HXSON (thermal enhanced extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-1-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.5	-	2.6	2.7	mm
E	package width	2.5	-	2.6	2.7	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	

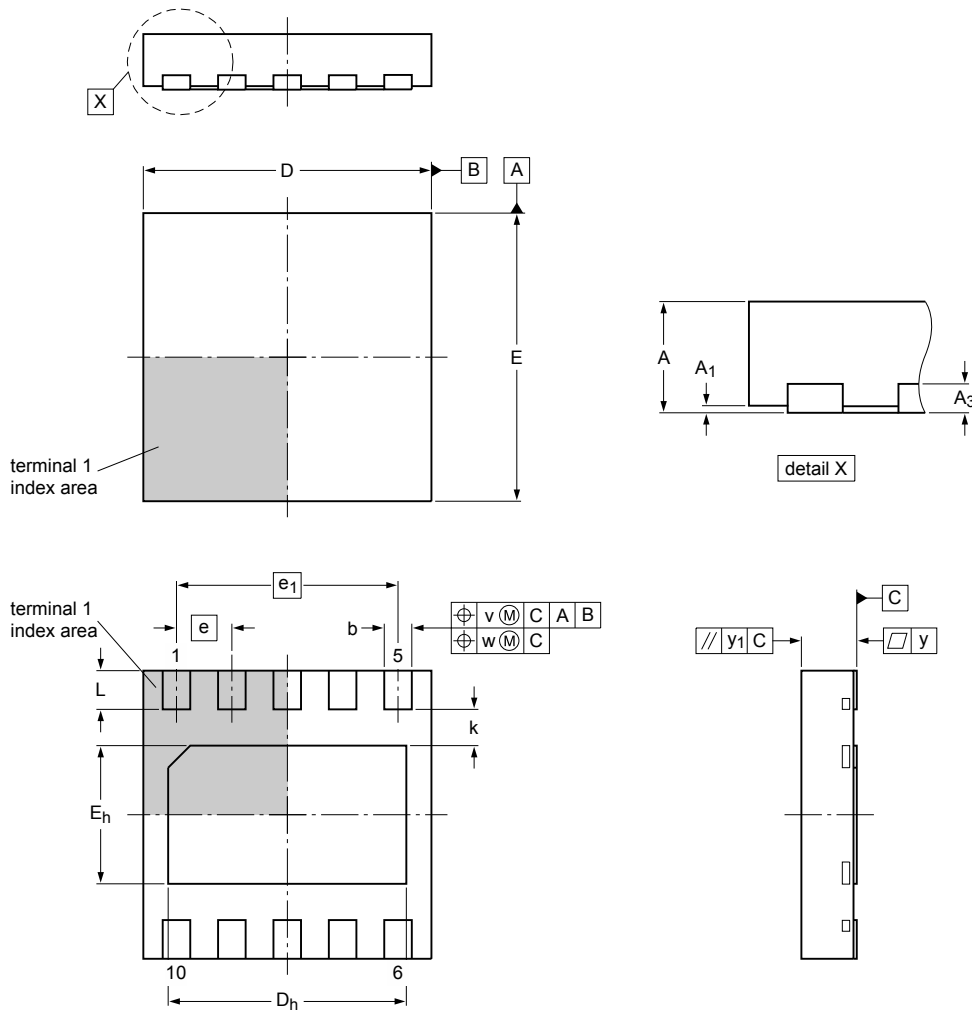


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2. Package outline

DFN2626-10: plastic thermal enhanced extremely thin small outline package; no leads; 10 terminals; body 2.6 x 2.6 x 0.5 mm

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Dimensions

Unit <sup>(1)</sup>	A	A <sub>1</sub>	A <sub>3</sub>	b	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	k	L	v	w	y	y <sub>1</sub>
max	0.5	0.05		0.30	2.7	2.20	2.7	1.30				0.40				
mm nom			0.127	0.25	2.6	2.15	2.6	1.25	0.5	2		0.35	0.1	0.05	0.05	0.05
min		0.00		0.20	2.5	2.10	2.5	1.20			0.2	0.30				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1197-1	---	---	---		11-01-20-12-09-16

Fig. 1. Package outline DFN2626-10 (SOT1197-1)

### 3. Soldering

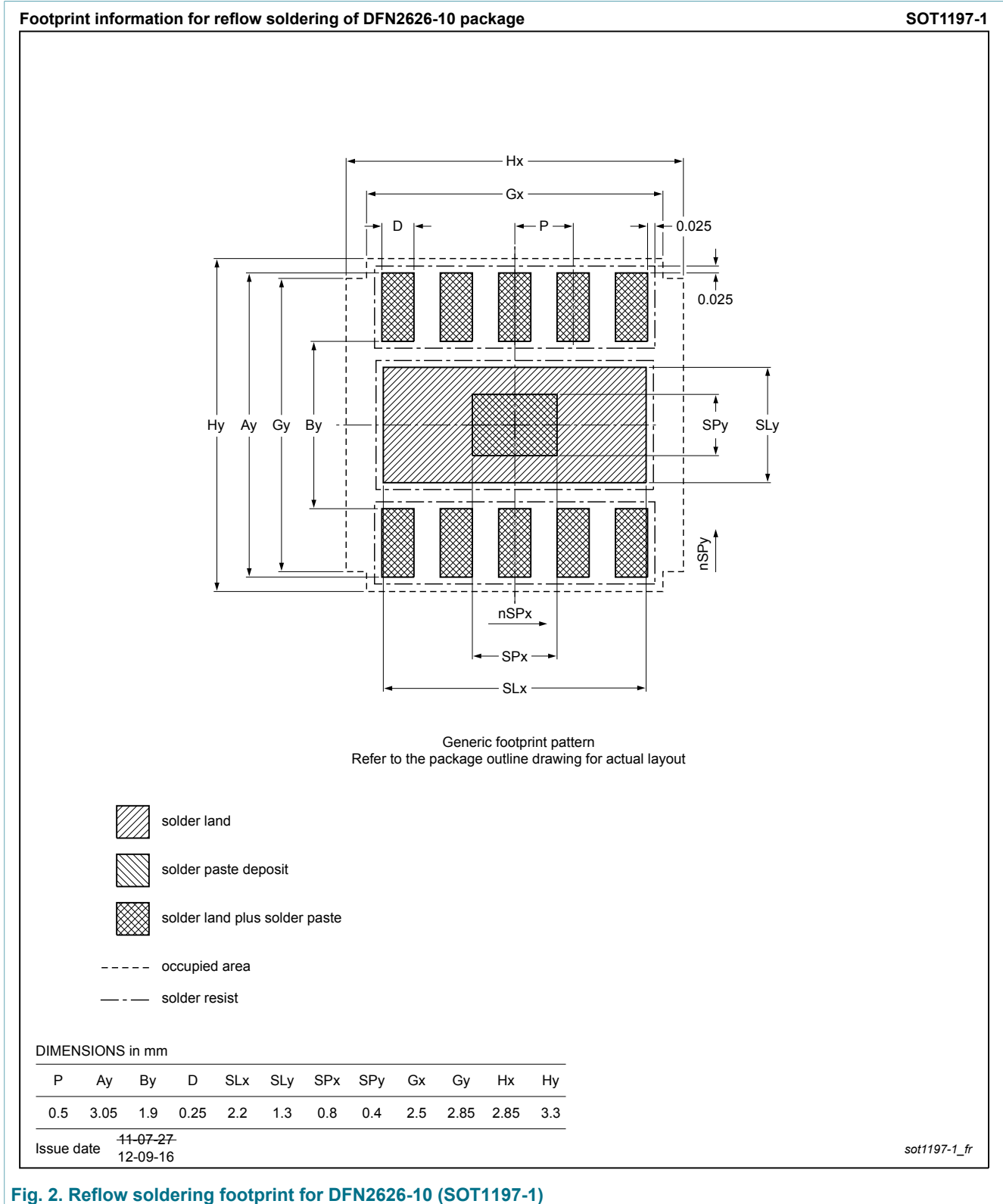


Fig. 2. Reflow soldering footprint for DFN2626-10 (SOT1197-1)

## 4. Legal information

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